Title (en)

METHODS FOR PROCESSING A SUBSTRATE

Title (de)

VERFAHREN ZUR VERARBEITUNG EINES SUBSTRATS

Title (fr)

PROCÉDÉS DE TRAITEMENT D'UN SUBSTRAT

Publication

EP 3406112 A1 20181128 (EN)

Application

EP 17703280 A 20170119

Priority

- US 201662281302 P 20160121
- US 2017014042 W 20170119

Abstract (en)

[origin: WO2017127489A1] Methods include processing a substrate including a step of pressing a wedge against at least an outer portion of a carrier bonded to the substrate. The method further includes a step of initiating debonding at a location of an outer peripheral bonded interface between the substrate and the carrier. The step of initiating debonding is achieved by providing relative movement between the wedge and an outer edge portion of the substrate.

IPC 8 full level

H05K 1/03 (2006.01); **H05K 3/00** (2006.01)

CPC (source: EP KR)

B32B 7/06 (2013.01 - EP KR); **B32B 17/06** (2013.01 - EP KR); **B32B 43/006** (2013.01 - EP KR); **G02F 1/133305** (2013.01 - EP); **H01L 21/6835** (2013.01 - EP); **H05K 1/0306** (2013.01 - EP); **H05K 3/007** (2013.01 - EP); B32B 2457/20 (2013.01 - EP KR); G02F 1/1303 (2013.01 - EP); H01L 2221/6835 (2013.01 - EP); H01L 2221/68381 (2013.01 - EP); H05K 2203/0264 (2013.01 - EP); H05K 2203/085 (2013.01 - EP)

Citation (search report)

See references of WO 2017127489A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2017127489 A1 20170727; CN 108781504 A 20181109; EP 3406112 A1 20181128; KR 20180104674 A 20180921; TW 201737766 A 20171016

DOCDB simple family (application)

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